



HB14 Ball Bonder



- + 17µ to 50µ Gold Wire
- + 6,5" TFT Touch panel operation System
- + Deep-access Bond Head 16 mm
- + Bond arm length 165 mm
- + 100 Program storage capacities
- + Heater stage Controller
- + Built in Dual Fiber Optic illuminator
- + Motorised Z Bond Head
- + Motorized Y travel for Step-Back loop control
- + Motorized 2" Wire Spool Holder
- + 6:1 ratio X-Y manipulator
- + High/Low Ultrasonic Selector 1 or 2 watt
- + FDD 3,25" to store Bonding programs
- + Electronic ball size control
- + Loop Profile Programmable
- + Stitch bonding and Bumpbonding
- + Semi-auto, Step and Manual Bonding Mode

HB14 Thermosonic Ball Bonder

The HB14 is a bench top size wire bonder, easy to operate and ideal for laboratories, pilot and pre-production runs and small scale production lines.

One Bond head for wire bonding in Ball/Wedge or Bump bonding mode.

Easy operation with TFT Touch Panel Operator System

Standard

6,5" TFT Touch panel operation System
90° Bonding Deep-access Bond Head
PLL Control Ultrasonic generator
High/Low Ultrasonic Power Selector (1/2 watt)
Large bonding area
Stitch bonding and Bump bonding
Bond arm length 165 mm
100 Program storage capacities
FDD 3,25" to store Bonding programs
Built in Dual Fiber Optic illuminator
Built in Heater stage Controller
Motorised 2" Wire Spool / Motorised Z & Y
Semi-automatic, Step and manual bonding
Electronic ball size control
Loop Profile Software

Options

H10 Zoom Stereo-Microscope Leica S6 20x
H21 100 x 100 mm Adjustable height heated work stage
H26 Adjustable height heated work stage surface 60 mm ø
H29 Adjustable height heated work stage surface 90 mm ø
H30 Additional Soft & Hardware for Wedge Bonding
H40 Tool Heater and Temperature Controller
with LCD Display
H50 Spot light targeting System
H51 Manual Z control
H60 Bonding tool for 25µ wire
H70 Gold-Wire 25µ, 60 Meter, 2" Spool
H72 ½ " Wire Spool adapter
H73 Torque Wrench 25 cNm for Bonding Tool
H90 Delivery with installation and 1 day Training

Technical Specifications

Ultrasonic system	PLL Control 62 kHz transducer
Ultrasonic power	0 - 1 watt Low / 0 - 2 watt High output
Bond time	15 - 2000 msec.
Bond force	15 - 150 cNm
Bonding Tool	1,58 Dia. X 19 mm length (0,0624" Dia. x 0,75")
Gold wire diameter	17 to 50µ (0,7 to 2 mil)
Motorised Wire Spool	50,8 mm (2 inch)
Wire termination	Bond Head tear or Table tear
Wire feed angle	90° for Wire and Ribbon
Motorized Y travel	stepback up to 7 mm (0,27")
Motorized Z travel	15 mm (0,6")
Throat depth	165 mm (6,7")
Fine Table motion	10 mm (0,55 ")
Mouse ratio	6:1 (Option 4:1 , 3:1)
Temperature controller	up to 250°C +/- 1°C
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	680 mm (27")W x 640 mm (25") D x 490 mm (19") H
Weight	Shipping 60 kg Net 45 kg
Industry Standards	CE Standards



TPT Franz Hickmann
Lärchenweg 59a
D-85757 Karlsfeld
Tel.: +49 (0) 8131 / 58604
Fax: +49 (0) 8131 / 58654
www.tpt.de